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Cmt.

being formed of a precious metal and a second constituent Y  
being consumed during a soldering operation by one of reacting  
and being dissolved in materials which are to be joined, and  
said solder having a hypereutectic concentration of said  
second constituent Y;

a substrate; and

a semiconductor chip secured to said substrate by one of  
alloying and brazing using said solder,

said solder containing a gold-tin compound (AuSn) having a  
composition by weight of Au to Sn of 70 to 30 and forming a  
layer having a thickness of from about 1  $\mu\text{m}$  to about 2  $\mu\text{m}$ .